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ABSTRACT

The 21st Electronics Packaging Technology Conference (EPTC 2019) is an International event organized by the IEEE RLS/EPS/EDS Singapore Chapter and sponsored by IEEE Electronics Packaging Society (EPS).

EPTC 2019 will feature keynotes, technical sessions, short courses, forums, an exhibition, social and networking activities. It aims to provide a good coverage of technology developments in all areas of electronics packaging from design to manufacturing and operation. It is a major forum for the exchange of knowledge and provides opportunities to network and meet leading experts.

Abstracts are solicited to describe original and unpublished work. The abstract should be at least 500-750 words and it must clearly state the purpose, methodology, results (including data, drawings, graphs and photographs) and conclusion of the work. Key references to prior publications should be included in the abstract as well. Authors can choose between oral or interactive presentation. Accepted papers that are registered and presented (oral & interactive) at the conference will be qualified for publication in IEEE Xplore.

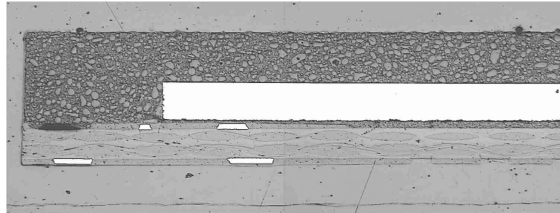

Fig. 1. Typical interface failure (Optional, for reference only)

Table 1. Package reliability result. (Optional, for reference only)

No	Test Description	Reliability Result
1	MST L3 85°C/60% RH with 3IR reflow 260°C based on J-STD-020	
2	Temperature cycling condition B –40 to 125°C for 1000 cycles based on EIA/JESD22-A105-B	
3	Thermal Shock Condition D –65 to 150°C for 700 cycles based on JESD22-A106-A	
4	Accelerated Moisture Resistance – Unbiased autoclave condition C 121°C/100% RH 96hrs based on JESD22-A102-B	

References (Optional, for reference only)

1. Wasserman, Y, "Integrated Single-Wafer RP Solutions for 0.25-micron Technologies," *IEEE Trans-CPMT-A*, Vol. 17, No. 3 (1995), pp. 346-351. [A reference to a journal article …]
2. Shu, William K., "PBGA Wire Bonding Development," *Proc 46th Electronic Components and Technology Conf*, Orlando, FL, May. 1996, pp. 219-225. [A reference to a presentation at a Conference…]